

Bill of Materials

TI DESIGNS

TIDEP0056

Item	Qty	Reference	Value	Part Description	Manufacturer	Manufacturer Part Number	Alternate Part	PCB Footprint	Note
1	1	2OR		Single 2-Input Positive-OR Gate,	Texas Instruments	SN74AHC1G32TDCKRQ1		DCK0005A_N	
2	2	3OR_1, 3OR_2		Single 3-Input Positive-OR Gate,	Texas Instruments	SN74LVC1G332DCKR		DCK0006A_N	
3	2	AND1, AND2		QUADRUPLE 2-INPUT POSITIVE-AND GATES, PW0014A	Texas Instruments	SN74AHC08PWR		PW0014A_N	
4	3	BUF1, BUF2, BUF3		Octal Buffer/Driver With 3-State Outputs	Texas Instruments	SN74LVC244APWRG3		PW20	
5	2	C1, C2		CAP, CERM, 10 μ F, 10 V, +/- 20%, X5R, 0402		CL05A106MP5NUNC		0402	
6	3	C3, C4, C5	0.1uF	Bypass capacitor				402	
7	1	C6	100uF	Bulk capacitor for motor drive				RD2055MD_250D	
8	2	C7, C9	10uF, 10V	Low-ESR ceramic bypass capacitor				805	
9	2	C8, C10	2.2uF, 6.3V	No Description				402	
10	1	C11		CAP, CERM, 0.1 μ F, 10 V, +/- 10%, X5R, 0201		CL03A104KP3NNNC		0201	
11	9	C12, C13, C14, C15, C16,	1000pF	Recommended filter capacitors for				402	
12	1	C21	0.1uF, 16V	Bypass capacitor				402	
13	2	DRV1, DRV2		1A Low Voltage Stepper or Single/Dual Brushed DC Motor Driver (PWM Ctrl)	Texas Instruments	DRV8833CPWPR		DRV8833CPWPR	
14	1	FPC_CUT		FPC connector for Fujitsu FTP-628MCL401 (Molex 52610-0871 is obsolete)	Molex	52610-0872		Molex 52610-0872	
15	1	FPC_HEAD		FPC connector for Fujitsu FTP-628MCL401 print head (Molex 52610-3071 is obsolete)	Molex	52610-3072		Molex 52610-3072	
16	2	P8, P9		CONN HEADER FMAL 46PS.1" DL GOLD				HDR2x23	
17	20	R1, R2, R3, R4, R5, R6, R7, R8, R9, R10, R11, R12, R13, R14, R15, R16, R17, R18, R19, R24	10k	RES 10K OHM 1/16W 5% 0402 SMD				402	
18	2	R20, R21	0.5	RES 10K OHM 1/16W 5% 0402 SMD				402	
19	2	R22, R23	20k	RES 10K OHM 1/16W 5% 0402 SMD				402	
20	1	R25		RES, 100 k, 0.1%, 0.1 W, 0603		RT0603BRD07100KL		0603	
21	1	Regulator 5V		3A Low Dropout Positive	Texas Instruments	LM1085IT-5.0/NOPB		T03B	

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